



CCLRC

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CMOS Image Sensors Technology

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Foundry A: 0.35 μm ; low dark current; stitching; (tape-out 1.6 Mpixel now);

5.5 and 15 μm epi available

0.18 μm in future ?

Foundry B: 0.18 μm CIS with pinned photodiode; stitching

5 μm epi. Outsourcing for large quantities

0.13 in development; production starts next year

Foundry D: 0.18 μm CIS; twin-, triple-well; pinned photodiode; stitching (?)

x μm epi.

Costs: MPW. A) £ 525/mm² (min 10 mm²) (£13000 / 5x5mm²)

B) £ 12,200 / 5x5 mm²

Engineering. A) 12 wafer lot; 4M: ~£60k non stitched; £65-77k stitched

B) 12 wafer lot; 4M: ~£115k non-stitched; ~145k stitched